Material declaration form

General Information

IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information	*: Required Field	

Supplier Information

Company name*	STMicroelectronics	Response Date*	2024-03-15
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	giovanni giacopello	Representative title	ADGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not Verified

Digitally signed by giovanni giacopello
Date: 2024.03.18 07:54:16 +01:00

Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STL125N10F8AG	BSY5*8D0FC42	A	3068	2024-03-15
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	114.00	mg	Each	ECOPACK® 2
Identity	**Authority**			
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
1	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM01056797	
Package designator	Package size	Number of instances	Shape	
QFN	6.00x5.00x1.00	8	Flat	
Comment	PowerFLAT 5x6 WF			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	**true**
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false

Exemption Id.	**Description**
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	**Response**
1 - Product(s) meets EU ELV requirements without any exemptions	false
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	**true**

Exemption Id.	**Description**
8(e)	8(e) - Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 25th Feb 2022	**Response**
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen	false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen	**true**

Substance	**amount in product (mg)**	**Application**	**ppm in product**
Nickel	0.095	die	833
Lead	3.187	soft solder	27956

QueryList : REACH-23rd January 2024				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				false
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	3.187	Soft solder	27956
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				false
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material
Lead	1000 ppm	3.187	Soft solder	920566

QueryList : Responsible metals sourcing	**Response**
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	**Gold, Tin, Tungsten,**

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	**Response**
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	**Response**
The product contains adhesives identified under GB 33372	false

Stockholm Convention Persistent Organic Pollutants	**Response**
Product is compliant with Stockholm Convention Persistent Organic Pollutants Annex I	true

QueryList : EUSRR Directive				**Response**
Product contains hazardous materials listed in EUSRR Annex II				True
The material present in the product is:				Lead
PFAS/PTFE Restriction				**Response**
Product contains Per- and Polyfluorinated Substance				False
BPA Restriction				**Response**
Product contains Bisphenol A (Isopropylidenediphenol)				False

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**BSY5*8D0FC42**					
Homogeneous material	**Material group**	**Mass**	**Unit of measure**	**Level**	**Substance category**	**Substance**	**CAS**	**Exempt**	**Mass**	**Unit of measure**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die	M-011 Other inorganic materials	3.525	mg	supplier	die	Silicon(Si)	7440-21-3		2.441	mg	692482	21412
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.229	mg	64965	2009
				supplier	metallisation	Copper(Cu)	7440-50-8		0.423	mg	120000	3711
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.095	mg	26950	833
				supplier	metallisation	Silver(Ag)	7440-22-4		0.112	mg	31773	982
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.028	mg	7943	246
				supplier	metallisation	Tungsten(W)	7440-33-7		0.043	mg	12199	377
				supplier	metallisation	Vanadium(V)	7440-62-2		0.003	mg	851	26
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.014	mg	3972	123
				supplier	passivation	Silicon oxide	7631-86-9		0.092	mg	26099	807
				supplier	polymer coating	polyimide	proprietary		0.045	mg	12766	395
Leadframe	M-004 Copper and its alloys	48.040	mg	supplier	alloy	Copper(Cu)	7440-50-8		46.134	mg	960325	404684
				supplier	alloy	Iron(Fe)	7439-89-6		1.085	mg	22585	9518
				supplier	alloy	Iron phosphide	1310-43-6		0.065	mg	1353	570
				supplier	alloy	Zinc(Zn)	7440-66-6		0.057	mg	1187	500
				supplier	metallization	Silver (Ag)	7440-22-4		0.699	mg	14550	6132
Soft solder	Solder	3.462	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temperat	3.187	mg	920567	27956
				supplier	solder	Tin(Sn)	7440-31-5		0.172	mg	49682	1509
				supplier	solder	Silver(Ag)	7440-22-4		0.086	mg	24841	754
				supplier	solder	dry flux residue	proprietary		0.017	mg	4910	149
Bonding wires	M-008 Precious metals	0.096	mg	supplier	wire	Gold(Au)	7440-57-5		0.096	mg	1000000	842
Encapsulation	M-011 Other inorganic materials	58.852	mg	supplier	mold compound	Silica vitreous	60676-86-0		46.199	mg	785003	405254
				supplier	mold compound	Epoxy type resin	25068-38-6		7.651	mg	130004	67114
				supplier	mold compound	Phenolic resin	9003-35-4		3.531	mg	59998	30974
				supplier	mold compound	Metal hydroxide	21645-51-2		1.177	mg	19999	10325
				supplier	mold compound	Carbon black	1333-86-4		0.294	mg	4996	2579
Connections coating	Solder	0.025	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.025	mg	1000000	219